## N-Ch 100V Fast Switching MOSFET <br> Vds=100V, Id=40A, RDS(oN) $=22 \mathrm{~m} \Omega$

## $>$ General Description

This PAN00TP26P N-Channel enhancement mode power field effect transistor is the high density trench technology and this advanced technology can provide excellent Rds(On) performance and efficiency for power switching and load switching application., this device also comply with the RoHS and Green Product requirement with full function reliability approved.

## Feature

- Super Low Gate Charge
-Green Device Available Excellent
-Cdv/dt effect decline
-Advanced high cell densit Trench
-TO-263-2L package design

TO-263-2L



## - Application

ODC-DC Converters
-Power Management
-Analog Switch

## > Absolute Maximum Ratings

| Parameter | Symbol | Rating | Units |
| :---: | :---: | :---: | :---: |
| Drain-Source Voltage | Vos | 100 | V |
| Gate-Source Voltage | VGs | $\pm 20$ | V |
| Continuous Drain Current, VGs @ 10V1 | $\mathrm{lo} @ \mathrm{Tc}=25^{\circ} \mathrm{C}$ | 40 | A |
| Continuous Drain Current, VGs @ 10V 1 | $\mathrm{lo} @ \mathrm{Tc}=70^{\circ} \mathrm{C}$ | 22 | A |
| Pulsed Drain Current2 | Idm | 75 | A |
| Single Pulse Avalanche Energy ${ }^{\text {a }}$ | EAS | 16 | mJ |
| Avalanche Current | las | 18 | A |
| Total Power Dissipation4 | Pb@Tc= $25^{\circ} \mathrm{C}$ | 62.5 | W |
| Storage Temperature Range | Tsta | -55 to 150 | ${ }^{\circ} \mathrm{C}$ |
| Operating Junction Temperature Range | TJ | -55 to 150 | ${ }^{\circ} \mathrm{C}$ |
| Thermal Resistance Junction-Ambient 1 | Rөja | 50 | C/W |
| Thermal Resistance Junction-Case ${ }_{1}$ | Rejc | 2 | ${ }^{\circ} \mathrm{C} / \mathrm{W}$ |

PAN00TP26P

## Electrical Characteristics ( $\mathrm{T}_{\mathrm{J}}=\mathbf{2 5 ^ { \circ } \mathrm { C } \text { Unless otherwise noted) }}$

| Parameter | Symbol | Conditions | Min. | Typ. | Max. | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Drain-Source Breakdown Voltage | BVoss | VGs=0V , Id=250uA | 100 | --- | --- | V |
| Static Drain-Source On-Resistance2 | Rds(0n) | VGs=10V , ld =9A | --- | 16 | 22 | $\mathrm{m} \Omega$ |
|  |  | VGs=4.5V , Id=7A | --- | 20 | 28 |  |
| Gate Threshold Voltage | VGS(th) | VGs=Vds, Id =250uA | 1.2 | --- | 2.5 | V |
| Drain-Source Leakage Current | Idss | V $\mathrm{DS}=80 \mathrm{~V}$, $\mathrm{VGS}=0 \mathrm{~V}, \mathrm{TJ}=25^{\circ} \mathrm{C}$ | --- | --- | 1 | uA |
|  |  | Vds $=80 \mathrm{~V}, \mathrm{VGS}=0 \mathrm{~V}, \mathrm{TJ}=55^{\circ} \mathrm{C}$ | --- | --- | 100 |  |
| Gate-Source Leakage Current | Igss | $\mathrm{V}_{\mathrm{GS}}= \pm 20 \mathrm{~V}, \mathrm{VDS}=0 \mathrm{~V}$ | --- | --- | $\pm 100$ | nA |
| Forward Transconductance | gfs | Vos $=5 \mathrm{~V}$, Id=9 | --- | 28 | --- | S |
| Gate Resistance | Rg | Vds=0V , VGS $=0 \mathrm{~V}$, $\mathrm{f}=1 \mathrm{MHz}$ | --- | 1.6 | --- | $\Omega$ |
| Total Gate Charge (10V) | $\mathrm{Qg}_{\mathrm{g}}$ | Vds $=80 \mathrm{~V}, \mathrm{VGS}=10 \mathrm{~V}$, ID=7A | --- | 36 | --- | nC |
| Gate-Source Charge | Qgs |  | --- | 5 | --- |  |
| Gate-Drain Charge | Qgd |  | --- | 10 | --- |  |
| Turn-On Delay Time | Td(on) | $\begin{aligned} & V_{D D}=50 \mathrm{~V}, \mathrm{VGS}_{\mathrm{GS}}=10 \mathrm{~V}, \\ & \mathrm{RG}_{\mathrm{G}}=3.3 \Omega \mathrm{ID}_{\mathrm{D}} \mathrm{~A} \end{aligned}$ | --- | 11.5 | --- | ns |
| Rise Time | Tr |  | --- | 29 | --- |  |
| Turn-Off Delay Time | $\mathrm{Td}_{\text {(off) }}$ |  | --- | 42 | --- |  |
| Fall Time | Tf |  | --- | 18 | --- |  |
| Input Capacitance | Ciss | V $\mathrm{DS}=15 \mathrm{~V}, \mathrm{VGS}=0 \mathrm{~V}, \mathrm{f}=1 \mathrm{MHz}$ | --- | 1930 | --- | pF |
| Output Capacitance | Coss |  | --- | 245 | --- |  |
| Reverse Transfer Capacitance | Crss |  | --- | 125 | --- |  |

## Diode Characteristics

| Parameter | Symbol | Conditions | Min. | Typ. | Max. | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Continuous Source Current1,6 | Is | $\mathrm{V}_{\mathrm{G}}=\mathrm{V}_{\mathrm{D}}=0 \mathrm{~V}$, Force Current | --- | --- | 40 | A |
| Pulsed Source Current2,6 | Ism |  | --- | --- | 75 | A |
| Diode Forward Voltage 2 | Vsd | $\mathrm{V}_{\mathrm{Gs}}=0 \mathrm{~V}, \mathrm{Is}=1 \mathrm{~A}, \mathrm{~T}=25^{\circ} \mathrm{C}$ | --- | --- | 1.2 | V |
| Reverse Recovery Time | tr | $\begin{aligned} & \mathrm{IF}=7 \mathrm{~A}, \mathrm{di} / \mathrm{dt}=100 \mathrm{~A} / \mu \mathrm{s}, \\ & \mathrm{~T}=25^{\circ} \mathrm{C} \end{aligned}$ | --- | 48 | --- | nS |
| Reverse Recovery Charge | Qrr |  | --- | 29 | --- | nC |

Note :
1.Pulse width limited by maximum junction temperature.
2.The data tested by pulsed, pulse width $\leqq 300$ us, duty cycle $\leqq 2 \%$
3.The EAS data shows Max. rating . The test condition is $\mathrm{V}_{\mathrm{DD}}=25 \mathrm{~V}, \mathrm{VGS}=10 \mathrm{~V}, \mathrm{~L}=0.1 \mathrm{mH}, \mathrm{I}_{\mathrm{AS}}=18 \mathrm{~A}$
4.Ensure that the channel temperature does not exceed $150^{\circ} \mathrm{C}$.
5. The data is theoretically the same as ID and IDM , in real applications, should be limited by total power dissipation.

## Typical Characteristics



Fig. 1 Typical Output Characteristics


Fig. 3 Forward Characteristics of Reverse


Fig. 5 Normalized $\mathrm{V}_{\mathrm{GS}(\mathrm{th})}$ vs. $\mathrm{T}_{\mathrm{J}}$


Fig. 2 On-Resistance vs. Gate-Source Voltage


Fig. 4 Gate-Charge Characteristics


Fig. 6 Normalized RDson vs. $\mathrm{T}_{\mathrm{J}}$

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$V_{\text {Ds }}=100 \mathrm{~V}, I_{D}=40 \mathrm{~A}$, RDS $(0 \mathrm{O})=22 \mathrm{~m} \Omega$


Fig. 7 Capacitance


Fig. 8 Safe Operating Area


Fig. 9 Normalized Maximum Transient Thermal Impedance


Fig. 10 Switching Time Waveform


Fig. 11 Unclamped Inductive Switching Waveform

## $>$ Recommand IR Reflow Soldering Thermal Profile



| Profile Feature | Pb-Free Assembly Profile |
| :--- | :---: |
| Temperature Min. (Tsmin) | $150^{\circ} \mathrm{C}$ |
| Temperature Max. (Tsmax) | $200^{\circ} \mathrm{C}$ |
| Time (ts) from (Tsmin to Tsmax) | $60-120$ seconds |
| Average Ramp-up Rate (tLto tP) | $3^{\circ} \mathrm{C} /$ second max. |
| Liquidous Temperature (TL) | $217^{\circ} \mathrm{C}$ |
| Time (tL) Maintained Above (TL) | $60-150$ seconds |
| Peak Temperature | $260^{\circ} \mathrm{C}+0^{\circ} \mathrm{C} /-5^{\circ} \mathrm{C}$ |
| Time (tP) within $5^{\circ} \mathrm{C}$ of actual Peak Temperature | 30 seconds |
| Ramp-down Rate (TP to TL) | $6^{\circ} \mathrm{C} /$ second max |
| Time $25^{\circ} \mathrm{C}$ to Peak Temperature | 8 minutes max. |

## Ordering Information

| Part Number | Description | Quantity |
| :---: | :---: | :---: |
| PAN00TP26P | TO-263-2L Reel | 800 pcs |

PAN00TP26P

## N-Ch 100V Fast Switching MOSFET

Vds=100V, Id=40A ,RDS(oN)=22m $\Omega$

## $>$ Package Information (TO-263-2L )



| SYMBOLS | MILLIMETERS |  | INCHES |  |
| :---: | :---: | :---: | :---: | :---: |
|  | MIN | MAX | MIN | MAX |
| A | 4.370 | 4.770 | 0.172 | 0.188 |
| A1 | 1.220 | 1.420 | 0.048 | 0.056 |
| A2 | 2.200 | 2.890 | 0.087 | 0.114 |
| A3 | 0.000 | 0.250 | 0.000 | 0.010 |
| b | 0.700 | 0.960 | 0.028 | 0.038 |
| b1 | 1.170 | 1.470 | 0.046 | 0.058 |
| c | 0.300 | 0.530 | 0.012 | 0.021 |
| D1 | 8.500 | 9.300 | 0.335 | 0.366 |
| D4 | 6.600 | - | 0.260 | - |
| E | 9.860 | 10.36 | 0.388 | 0.408 |
| E5 | 7.060 | - | 0.278 | - |
| e | 2.540 BSC |  | 0.100 BSC |  |
| H | 14.70 | 15.70 | 0.579 | 0.618 |
| H2 | 1.070 | 1.470 | 0.042 | 0.058 |
| L | 2.000 | 2.600 | 0.079 | 0.102 |
| L1 | 1.400 | 1.750 | 0.055 | 0.069 |
| L4 | 0.250 BSC |  | 0.010 BSC |  |
| $\bigcirc$ | $0^{\circ}$ | $9{ }^{\circ}$ | $0^{\circ}$ | $9^{\circ}$ |

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